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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Betuils	
Product Status	Obsolete
Core Processor	TriCore™
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	CANbus, EBI/EMI, FIFO, I ² C, IrDA, SPI, UART/USART, USB
Peripherals	DMA, POR, PWM, WDT
Number of I/O	72
Program Memory Size	-
Program Memory Type	ROMIess
EEPROM Size	-
RAM Size	144К х 8
Voltage - Supply (Vcc/Vdd)	1.43V ~ 1.58V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	208-LBGA
Supplier Device Package	P-LBGA-208-2
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/tc1130l100ebgbbfxuma1

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TC1130

Advance Information

General Device Information

2.3 Pin Configuration

	Α	В	С	D	E	F	G	н	J	к	L	М	N	Р	R	т	
16	Reser ved	P3.10	P3.11	P3.12	P2.15	P2.14	P2.11	P2.9	P2.8	P2.7	VDDOSC	XTAL1	XTAL2	V _{DD} OSC3	V _{SS}	Reser ved	16
15	P3.0	P3.1	P3.8	P3.2	P3.3	P3.6	P3.5	P3.9	P3.15	P2.12	V _{ss}	F0.3	P2.4	F0.1	F0.9	D-	15
14	P1.9	P1.10	P1.11	P1.14	P1.13	P1.15	P3.4	P3.7	P3.14	P2.13	HW CFG1	HW CFG0	P2.5	P2.3	F0.10	D+	14
13	P1.8	P1.7	P1.5	V _{DDP}	V _{SS}	P1.12	V _{DD}	V _{ss}	V _{DDP}	P3.13	P2.10	V _{SS}	V _{DDP}	P2.2	F0.8	TDI	13
12											n	P2.6	P2.0	P0.5	так	12	
11	BAA	ADV	P1.4	P1.0		С	onfig f		ion (t C113		iew)		P0.0	P2.1	P0.4	TRST	11
10	A17	A18	A19	A20			V _{DD}	V _{SS}	V _{SS}	V _{DD}			P0.7	P0.2	P0.6	πю	10
9	A16	WAIT	3	<u>C30</u>			V _{DD}	V _{SS}	V _{SS}	V _{DD}			P0.11	P0.12	P4.1	TMS	9
8	A15	cs	AD0	ଟ୍ଟ			V _{DD}	V _{SS}	V _{SS}	V _{DD}			P0.14	P0.13	P4.0	TRCLK	8
7	BC3	BC2	AD1	AD 16		V _{DD} V _{SS} V _{SS} V _{DD}								P0.15	P4.5	NMI	7
6	BC1	AD2	AD3	RAS										P4.4	P4.6	HW CFG2	6
5	BC0	AD17	AD4	CAS									HDRS	P4.7	PORST	BRKIN	5
4	AD18	AD 19	AD20	V _{DDP}	V _{SS}	AD28	AD29	V _{DDP}	V _{SS}	A14	OKE	V _{DDP}	V _{SS}	A23	A22	A21	4
3	AD5	AD21	AD7	AD25	AD11	AD 12	AD 15	AD 30	A10	A11	A12	A13		MR/W	ALE	RD/WR	3
2	AD6	AD22	AD8	AD 9	AD26	AD27	AD31	AD14	A5	A6	A7	A8	A9	RD	MII_ RXCLK	MII_ TXCLK	2
1	Reser ved	AD23	AD24	BFCLKI	BFCLKO	AD 10	AD13	SDOLKO	SDOLKI	AO	A1	A2	A3	A4	MII_ MDIO	Reser ved	1
	A	В	С	D	E	F	G	Н	J	к	L	М	Ν	Р	R	Т	
														MCF	-0495	0mod	
																	

Figure 2-3 TC1130 Pins: P-BGA-208 Package (top view)



General Device Information

Table 2-1Pin Definitions and Functions (cont'd)

Symbol	Pin	In Out	PU/ PD ¹⁾	Functions	
P0.12	P9		PUC	RXDCAN2 RCLK0A REQ4	CAN node 2 receiver input MLI0 receive channel clock input A External Trigger Input 4
P0.13	P8	0 0	PUC	TXDCAN2 REQ5 RREADY0A	CAN node 2 transmitter output External Trigger Input 5 MLI0 receive channel ready output A
P0.14	N8		PUC	RXDCAN3 REQ6 RVALID0A	CAN node 3 receiver input External Trigger Input 6 MLI0 receive channel valid input A
P0.15	P7	0 	PUC	TXDCAN3 REQ7 RDATA0A	CAN node 3 transmitter output External Trigger Input 7 MLI0 receive channel data input A



General Device Information

Table 2-1Pin Definitions and Functions (cont'd)

Symbol	Pin	In Out	PU/ PD ¹⁾	Functions	
P1.7	B13	I	PUC	MII_RXDV	Ethernet Controller receive data valid input line
		I		SWCFG7	Software configuration 7
		0		OCDSA_7	OCDS L2 Debug Line A7
P1.8	A13	I	PUC	MII_CRS	Ethernet Controller carrier input line
				SWCFG8	Software configuration 8
D / A		0		OCDSA_8	OCDS L2 Debug Line A8
P1.9	A14		PUC	MII_COL	Ethernet Controller collision input line
				SWCFG9	Software configuration 9
D1 10	D14	0		OCDSA_9	OCDS L2 Debug Line A9
P1.10	B14		PUC	MII_RXD0	Ethernet Controller receive data input line 0
		1		SWCFG10	Software configuration 10
		0		OCDSA_10	OCDS L2 Debug Line A10
P1.11	C14	1	PUC	MII_RXD1	Ethernet Controller receive data input line 1
		I		SWCFG11	Software configuration 11
		0		OCDSA_11	OCDS L2 Debug Line A1
		0		SLSO0_1	SSC0 Slave Select output 1
P1.12	F13	1	PUC	MII_RXD2	Ethernet Controller receive data input line 2
		I		SWCFG12	Software configuration 12
		0		OCDSA_12	OCDS L2 Debug Line A12
		0		SLSO1_1	SSC1 Slave Select output 1
P1.13	E14		PUC	MII_RXD3	Ethernet Controller receive data input line 3
		I		SWCFG13	Software configuration 13
		0		OCDSA_13	OCDS L2 Debug Line A13
		0		SLSO0_2	SSC0 Slave Select output 2
P1.14	D14	I	PUC	MII_RXER	Ethernet Controller receive error input line
		0		SLSO1_2	SSC1 Slave Select output 2
		I		SWCFG14	Software configuration 14
		0		OCDSA_14	OCDS L2 Debug Line A14
P1.15	F14	1	PUC	SLSI0	SSC0 Slave Select Input
		0		RMW	EBU Read Modify Write
		Ι		SWCFG15	Software configuration 15
		0		OCDSA_15	OCDS L2 Debug Line A15



General Device Information

Table 2-1 Pin Definitions and Functions (cont'd)

Symbol	Pin	In Out	PU/ PD ¹⁾	Functions			
P3		I/O		Port 3 Port 3 is a 16-bit bi-directional general purpose I/O port which can be alternatively used for MLI1, CCU61			
P3.0	A15	0	PUC	OCDSB_0 COUT61 3	OCDS Level 2 debug lines. OCDS L2 Debug Line B0 CCU61 compare channel 3 output		
P3.1	B15	0 I/O	PUC	OCDSB_1 CC61_0	OCDS L2 Debug Line B1 CCU61 input/output of capture/		
P3.2	D15	0 0	PUC	OCDSB_2 COUT61_0	compare channel 0 OCDS L2 Debug Line B2 CCU61 output of capture/compare		
P3.3	E15	0 I/O	PUC	OCDSB_3 CC61_1	channel 0 OCDS L2 Debug Line B3 CCU61 input/output of capture/		
P3.4	G14	0 0	PUC	OCDSB_4 COUT61_1	compare channel 1 OCDS L2 Debug Line B4 CCU61 output of capture/compare		
P3.5	G15	0 I/O	PUC	OCDSB_5 CC61_2	channel 1 OCDS L2 Debug Line B5 CCU61 input/output of capture/		
P3.6	F15	0 0	PUC	OCDSB_6 COUT61_2	compare channel 2 OCDS L2 Debug Line B6 CCU61 output of capture/compare		
P3.7	H14	0 I	PUC	OCDSB_7 CTRAP1	channel 2 OCDS L2 Debug Line B7 CCU61 trap input		
P3.8	C15	0 0 1 0	PUC	SLSO0_5 OCDSB_8 CCPOS1_0 TCLK1	SSC0 Slave Select output 5 OCDS L2 Debug Line B8 CCU61 Hall input signal 0 MLI1 transmit channel clock output		
P3.9	H15	0 0 1	PUC	SLSO1_5 OCDSB_9 CCPOS1_1 TREADY1	SSC1 Slave Select output 5 OCDS L2 Debug Line B9 CCU61 Hall input signal 1 MLI1 transmit channel ready input		
P3.10	B16	0 0 1 0 0	PUC	SLSO0_6 OCDSB_10 CCPOS1_2 TVALID1 SLSO1_6	SSC0 Slave Select output 6 OCDS L2 Debug Line B10 CCU61 Hall input signal 2 MLI1 transmit channel valid output SSC1 Slave Select output 6		



Functional Description

Features:

The FPI Bus is designed with the requirements of high-performance systems in mind. The features are:

- Core independent
- Multimaster capability (up to 16 masters)
- Demultiplexed operation
- Clock synchronous
- Peak transfer rate of up to 800 Mbytes/sec (@ 100 MHz bus clock)
- Address and data bus scalable (address bus up to 32 bits, data bus up to 64 bits)
- 8-/16-/32- and 64-bit data transfers
- · Broad range of transfer types from single to multiple data transfers
- · Split transaction support for agents with long response time
- Burst transfer capability
- EMI and power consumption minimized

3.4.3 LFI

The LMB-to-FPI Interface (LFI) block provides the circuitry to interface (bridge) the FPI bus and the Local Memory Bus (LMB).

LFI Features:

- Full support for bus transactions found within current TriCore[™] 1.3 based systems:
 - Single 8/16/32-bit Write/Read transfers from FPI to LMB
 - Single 8/16/32/64-bit Write/Read transfers from LMB to FPI
 - Read-Modify-Write transfers of 8/16/32-bit in both directions
 - Burst transactions of 2, 4 or 8 data beats from the FPI to the LMB
 - Burst transactions of 2 or 4 data beats from the LMB to the FPI
- Address decoding and translation as required by TriCore[™] 1.3 implementation
- · FPI master interface supports full pipelining on FPI bus
- LMB master interface supports pipelining on LMB within the scope of the LMB specification
- FPI master interface can act as default master on FPI bus
- Programmable support for split LMB to FPI read transactions
- Retry generation on both FPI and LMB buses
- Full support for abort, retry, error and FPI timeout conditions
- Flexible LMB/FPI clock ratio support including dynamic clock switching support
- LFI core clock may be shut down when no transactions are being issued to LFI from either bus and the LFI has no transactions in progress, thus saving power.



TC1130

Advance Information

Functional Description

3.5 LMB External Bus Unit

The LMB External Bus Control Unit (EBU) of the TC1130 is the interface between external resources, like memories and peripheral units, and the internal resources connected to on-chip buses if enabled. The basic structure and external interconnections of the EBU are shown in **Figure 3-1**.

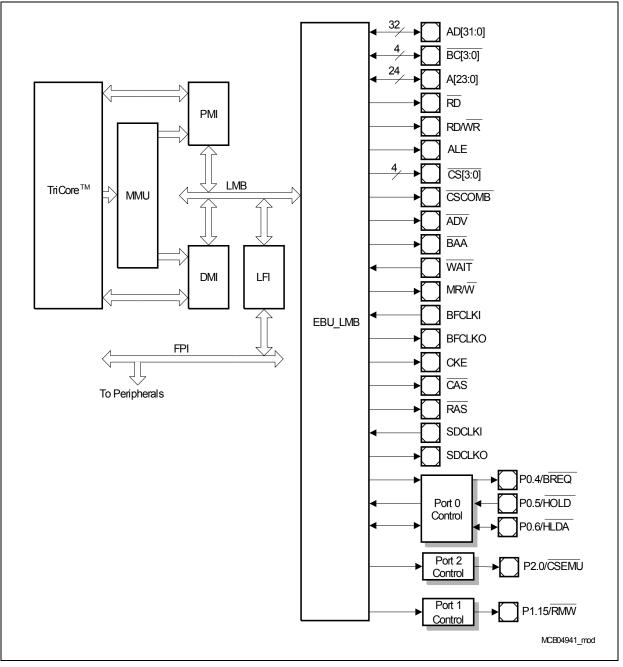


Figure 3-1 EBU Structure and Interface



Functional Description

3.7 Interrupt System

An interrupt request can be serviced by the CPU, which is called "Service Provider". Interrupt requests are referred to as "Service Requests" in this document.

Each peripheral in the TC1130 can generate service requests. Additionally, the Bus Control Unit, the Debug Unit, the DMA Controller and even the CPU itself can generate service requests to the Service Provider. As shown in **Figure 3-3**, each unit that can generate service requests is connected to one or multiple Service Request Nodes (SRN). Each SRN contains a Service Request Control Register mod_SRC, where "mod" is the identifier of the unit requesting service. The SRNs are connected to the Interrupt Control Unit (ICU) via the CPU Interrupt Arbitration Bus. The ICU arbitrates service requests for the CPU and administers the Interrupt Arbitration Bus.

Units that can generate service requests are:

- Asynchronous/Synchronous Serial Interfaces (ASC0, ASC1 and ASC2) with 4 SRNs each
- High-Speed Synchronous Serial Interfaces (SSC0 and SSC1) with 3 SRNs each
- Inter IC Interface (IIC) with 3 SRNs
- Universal Serial Bus (USB) with 8 SRNs
- Micro Link Interface MLI0 with 4 SRNs and MLI1 with 2 SRNs
- General Purpose Timer Unit (GPTU) with 8 SRNs
- Capture/Compare Unit (CCU60 and CCU61) with 4 SRNs each
- MultiCAN (CAN) with 16 SRNs
- Ethernet Controller with 9 SRNs
- External Interrupts with 4 SRNs
- Direct Memory Access Controller (DMA) with 4 SRNs
- DMA Bus with 1 SRN
- System Timer (STM) with 2 SRNs
- Bus Control Units (SBCU and LBCU) with 1 SRN each
- Central Processing Unit (CPU) with 4 SRNs
- Floating Point Unit (FPU) with 1 SRN
- Debug Unit (OCDS) with 1 SRN

The CPU can make service requests directly to itself (via the ICU). The CPU Service Request Nodes are activated through software.



Functional Description

3.8 Parallel Ports

The TC1130 has 72 digital input/output port lines, which are organized into four parallel 16-bit ports and one parallel 8-bit port, Port P0 to Port P4 with 3.3 V nominal voltage.

The digital parallel ports can be used as general purpose I/O lines or they can perform input/output functions for the on-chip peripheral units. An overview on the port-to-peripheral unit assignment is shown in **Figure 3-4**.

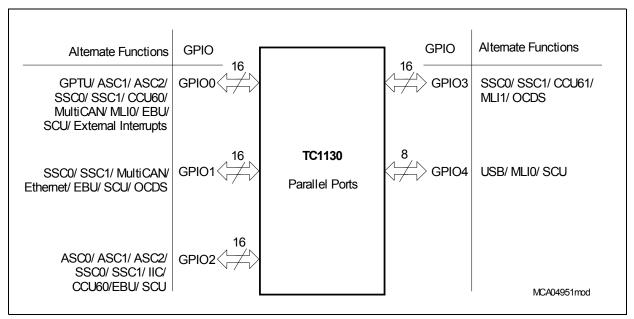


Figure 3-4 Parallel Ports of the TC1130



Functional Description

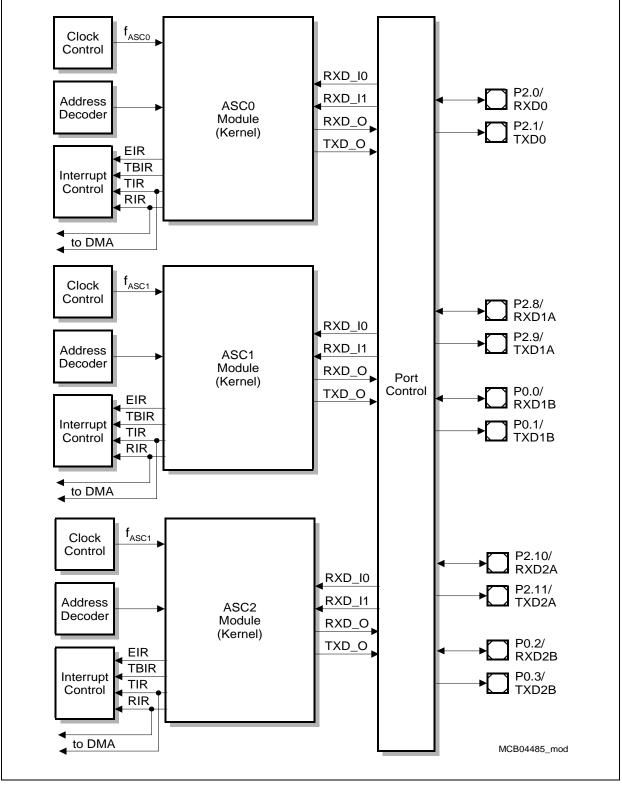


Figure 3-5 General Block Diagram of the ASC Interfaces



Functional Description

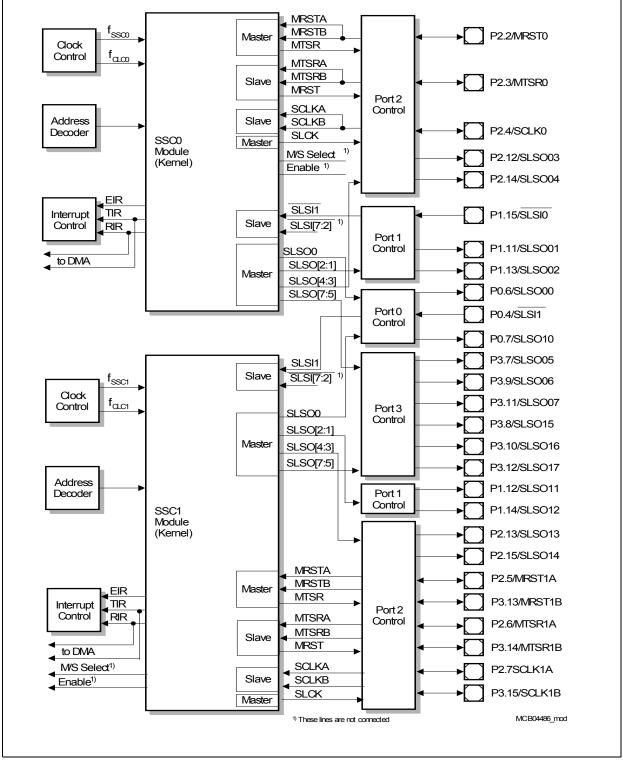


Figure 3-6 General Block Diagram of the SSC Interfaces



Functional Description

The bit timings for the CAN nodes are derived from the peripheral clock (f_{CAN}) and are programmable up to a data rate of 1 MBaud. A pair of receive and transmit pins connects each CAN node to a bus transceiver.

Features:

- Compliant to ISO 11898
- CAN functionality according to CAN specification V2.0 B (active)
- Dedicated control registers are provided for each CAN node
- A data transfer rate up to 1 MBaud is supported
- Flexible and powerful message transfer control and error handling capabilities are implemented
- Advanced CAN bus bit timing analysis and baud rate detection can be performed for each CAN node via the frame counter
- Full-CAN functionality: A set of 128 message objects can be individually
 - allocated (assigned) to any CAN node
 - configured as transmit or receive object
 - setup to handle frames with 11-bit or 29-bit identifier
 - counted or assigned a timestamp via a frame counter
 - configured to remote monitoring mode
- Advanced Acceptance Filtering:
 - Each message object provides an individual acceptance mask to filter incoming frames.
 - A message object can be configured to accept only standard or only extended frames or to accept both standard and extended frames.
 - Message objects can be grouped into 4 priority classes.
 - The selection of the message to be transmitted first can be performed on the basis of frame identifier, IDE bit and RTR bit according to CAN arbitration rules.
- Advanced Message Object Functionality:
 - Message objects can be combined to build FIFO message buffers of arbitrary size, which is only limited by the total number of message objects.
 - Message objects can be linked to form a gateway to automatically transfer frames between two different CAN buses. A single gateway can link any two CAN nodes. An arbitrary number of gateways may be defined.
- Advanced Data Management:
 - The Message objects are organized in double chained lists.
 - List reorganizations may be performed at any time, even during full operation of the CAN nodes.
 - A powerful, command driven list controller manages the organization of the list structure and ensures consistency of the list.
 - Message FIFOs are based on the list structure and can easily be scaled in size during CAN operation.



Functional Description

The Micro Link Serial Bus Interface is dedicated to the serial communication between the other Infineon 32-bit controllers with MLI. The communication is intended to be fast due to an address translation system, and it is not necessary to have any special program in the second controller.

Features:

- Serial communication from the MLI transmitter to MLI receiver of another controller
- Module supports connection of each MLI with up to four MLI from other controllers
- Fully transparent read/write access supported (= remote programming)
- Complete address range of target controller available
- Special protocol to transfer data, address offset, or address offset and data
- Error control using a parity bit
- 32-bit, 16-bit, and 8-bit data transfers
- · Address offset width: from 1- to 16-bit
- Baud rate: f_{MLI} / 2 (symmetric shift clock approach), baud rate definition by the corresponding fractional divider



Functional Description

RB and TB provide on-chip data buffering whereas DMUR and DMUT perform data transfer from/to the shared memory.

Two interfaces are provided by the Ethernet Controller module:

- MII interface for connection of Ethernet PHYs via 18 Input/Output lines
- Master/slave FPI bus interface for connection to the on-chip system bus for data transfer as well as configuration

Features:

- Media Independent Interface (MII) according to IEEE 802.3
- Supports 10 or 100 Mbit/sec MII-based Physical devices
- Supports Full Duplex Ethernet
- Supports data transfer between Ethernet Controller and COM-DRAM
- Supports data transfer between Ethernet Controller and SDRAM via EBU
- 256 x 32 bit Receive buffer and Transmit buffer each
- Supports burst transfers up to 8 x 32 Bytes

Media Access Controller (MAC)

- 100/10 Mbit/sec operations
- Full IEEE 802.3 compliance
- Station management signaling
- Large on-chip CAM (Content Addressable Memory)
- · Full duplex mode
- 80-byte transmit FIFO
- 16-byte receive FIFO
- PAUSE Operation
- Flexible MAC Control Support
- Supports Long Packet mode and Short Packet mode
- PAD generation

Media Independent Interface (MII)

- Media independence
- · Multi-vendor point of interoperability
- Supports connection of MAC layer and Physical (PHY) layer devices
- · Capable of supporting both 100 Mbit/sec and 10 Mbit/sec data rates
- Data and delimiters are synchronous to clock references
- Provides independent four bits wide transmit and receive data paths
- Supports connection of PHY layer and Station Management (STA) devices
- · Provides a simple management interface
- Capable of driving a limited length of shielded cable



Functional Description

TC1130

Table 3-5 Load Capacitors Select (cont'd)

Fundamental Mode Crystal Frequency (approx., MHz)	Load Capacitors C1, C2 (pF)				
20	10				
24	10				

A block capacitor between V_{DDOSC3} and $V_{SSOSC},\ V_{DDOSC}$ and V_{SSOSC} is recommended, too.



Electrical Parameters

4.2 DC Parameters

4.2.1 Input/Output Characteristics

$V_{SS} = 0 V; T_A = -40$	C to +125	Q
---------------------------	------------------	----------

Parameter	Symbol	Limit	Values	Unit	Test Condition						
		min.	max.								
GPIO pins, Dedicated pins and EBU pins											
Input low voltage	V _{IL} SR	-0.3	0.8	V	LvTTL						
Input high voltage	V _{IH} SR	2.0	V _{DDP} + 0.3	V	LvTTL						
Output low voltage	V _{OL} CC	_	0.4	V	I _{OL} = 2mA						
Output high voltage	V _{OH} CC	2.4	-	V	I _{OH} = -2mA						
Pull-up current 1)	I _{PUA} CC			А	V _{IN} = 0V						
	I _{PUC} CC			Α	V _{IN} = 0V						
Pull-down current ²⁾	I _{PDA} CC	-	156	FA	$V_{IN} = V_{DDP}$						
	I _{PDC} CC	-	15.7	F A	$V_{IN} = V_{DDP}$						
Input leakage current 3)	I _{OZ1} CC	-	r350	nA	$0 < V_{IN} < V_{DDP}$						
Pin Capacitance ⁴⁾	C _{IO} CC	_	10	pF	f = 1 MHz T _A = 25 C						

¹⁾ The current is applicable to the pins, for which a pull-up has been specified. Refer to Table 2-1. I_{PUx} refers to the pull-up current for type x in absolute values.

²⁾ The current is applicable to the pins, for which a pull-down has been specified. Refer to Table 2-1. I_{PDx} refers to the pull-down current for type x in absolute values.

³⁾ Excluded following pins: NMI, TRST, TCK, TDI, TMS, MII_TXCLK, MII_RXCLK, MII_MDIO, ALE, P2.1,HWCFG0, HWCFG1, HWCFG2, BRKIN, PORST, HDRST.

⁴⁾ Not subject to production test, verified by design/characterization.

TC1130

Electrical Parameters